1. Part No. Expression:

## PIAQ1004S1R0MN

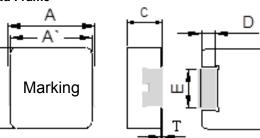
	(a)	(b)	(C)	(d)	(e)(f)
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- a) Series Code
- b) Dimension Code
- c) Type Code d) Inductance Code
- e) Tolerance Code
- f) Internal Control Code

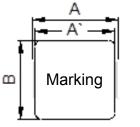
### 2. Configuration & Dimensions:

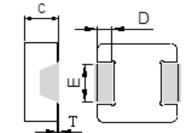
Lead Frame a.

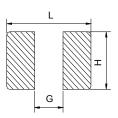
m



b. Non Lead Frame







**Recommend PC Board Pattern** 

Note:

The above PCB layout is for reference only.
Solder paste thickness of 0.15mm and above is recommended.

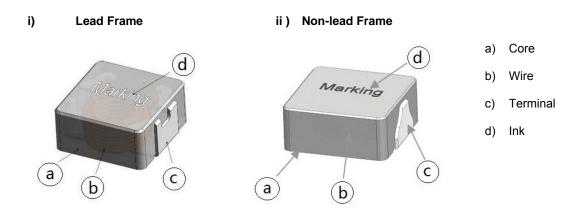
Unit: mm

А	A`	В	С	D	Т	G	Н	L	E	Inductance
44.0.0.0		10.0.0		0.0.0	0.00	5 4 2	2 5	12.5	2.5±0.3	Between 0.56-1.50uH
11.0±0.3	10.0±0.3	10.0±0.3	3.8±0.2	2.0±0.3	0 - 0.2	5.4	3.5		3.0±0.3	0.47uH and below 2.20uH and above

## 3. Schematic:



# 4. Material List:



### 5. General Specification:

- (a) Reliability test for this part meets AEC-Q200 standard.
- (b) Operating Temp. : -55°C to +155°C (Inclusive of coil temp rise)
- (c) Storage Temp. : -55°C to +155°C (on board)
- (d) Humidity Range : 85 ± 3% RH
- (e) Heat Rated Current (Irms) will cause the coil temperature rise approximately Δt of 40°C (keep 1min)
- (f) Saturation Current (Isat Typ.) will cause L0 to drop approximately 30%.
- (g) Part Temp. (Ambient + Temp. Rise) should not exceed 155°C under worst case operating conditions.
- (h) Storage condition (component in its packaging)
  - i) Temperature: -10 to 40°C
  - ii) Humidity : 50~60% RH

# 6. Electrical Characteristics:

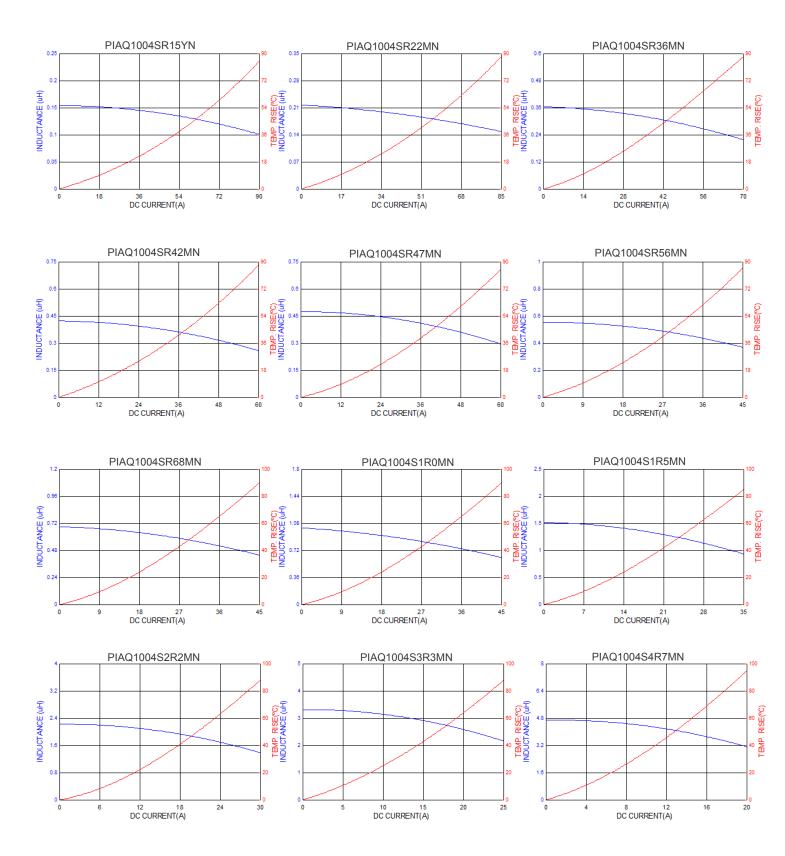
Part Number	Inductance Lo (uH) @ 0A	Test Frequency, L	Heat F Curre (A) Typ.	nt DČ	Curre	ration nt DC Isat. Max.	DCR (mΩ)Typ.	DCR (mΩ)Max.	Туре
PIAQ1004SR15YN	0.15	100kHz/1.0V	тур. 44	38	82	75	0.5	0.6	Non lead frame
PIAQ1004SR22MN	0.22	100kHz/1.0V	36	33	70	60	0.72	0.83	Non lead frame
PIAQ1004SR36MN	0.36	100kHz/1.0V	33	29	51	45	1.05	1.18	Non lead frame
PIAQ1004SR42MN	0.42	100kHz/1.0V	32.5	28.5	50	42	1.15	1.3	Non lead frame
PIAQ1004SR47MN	0.47	100kHz/1.0V	32	28	46	40	1.3	1.5	Non lead frame
PIAQ1004SR56MN	0.56	100kHz/1.0V	25	23	34	29	1.6	1.8	Non lead frame
PIAQ1004SR68MN	0.68	100kHz/1.0V	23	20	31	28	1.9	2.2	Non lead frame
PIAQ1004S1R0MN	1.00	100kHz/1.0V	20	18	29	26	2.9	3.25	Non lead frame
PIAQ1004S1R5MN	1.50	100kHz/1.0V	17.5	16	26	22	3.7	4.2	Non lead frame
PIAQ1004S2R2MN	2.20	100kHz/1.0V	15	13	20	16	5.8	6.7	Lead frame
PIAQ1004S3R3MN	3.30	100kHz/1.0V	11	10	17.5	14	10.5	11.8	Lead frame
PIAQ1004S4R7MN	4.70	100kHz/1.0V	8.8	8.0	15.2	13	15.8	19	Lead frame
PIAQ1004S5R6MN	5.60	100kHz/1.0V	8.0	7.2	14.1	11.5	19	22.8	Lead frame
PIAQ1004S6R8MN	6.80	100kHz/1.0V	7.8	6.8	12.2	11	22	24.5	Lead frame
PIAQ1004S8R2MN	8.20	100kHz/1.0V	7.6	6.5	9.5	8.5	25	28	Lead frame
PIAQ1004S100MN	10.0	100kHz/1.0V	7.5	6.1	8.6	7.5	27	30	Lead frame
PIAQ1004S150MN	15.0	100kHz/1.0V	6.25	5.0	7.0	6.0	41	45	Lead frame
PIAQ1004S220MN	22.0	100kHz/1.0V	5.0	4.1	6.2	5.5	58	66	Lead frame
PIAQ1004S330MN	33.0	100kHz/1.0V	4.4	3.5	5.5	5.0	84	91	Lead frame
PIAQ1004S470MN	47.0	100kHz/1.0V	3.5	3.0	4.0	3.7	125	143	Lead frame
PIAQ1004S680MN	68.0	100kHz/1.0V	2.6	2.4	3.2	3.0	184	210	Lead frame
PIAQ1004S820MN	82.0	100kHz/1.0V	2.3	2.1	3	2.8	240	270	Lead frame
PIAQ1004S101MN	100.0	100kHz/1.0V	2.0	1.8	2.7	2.4	270	310	Lead frame

\*Tolerance code : M =  $\pm 20\%$ , Y=  $\pm 30\%$ 

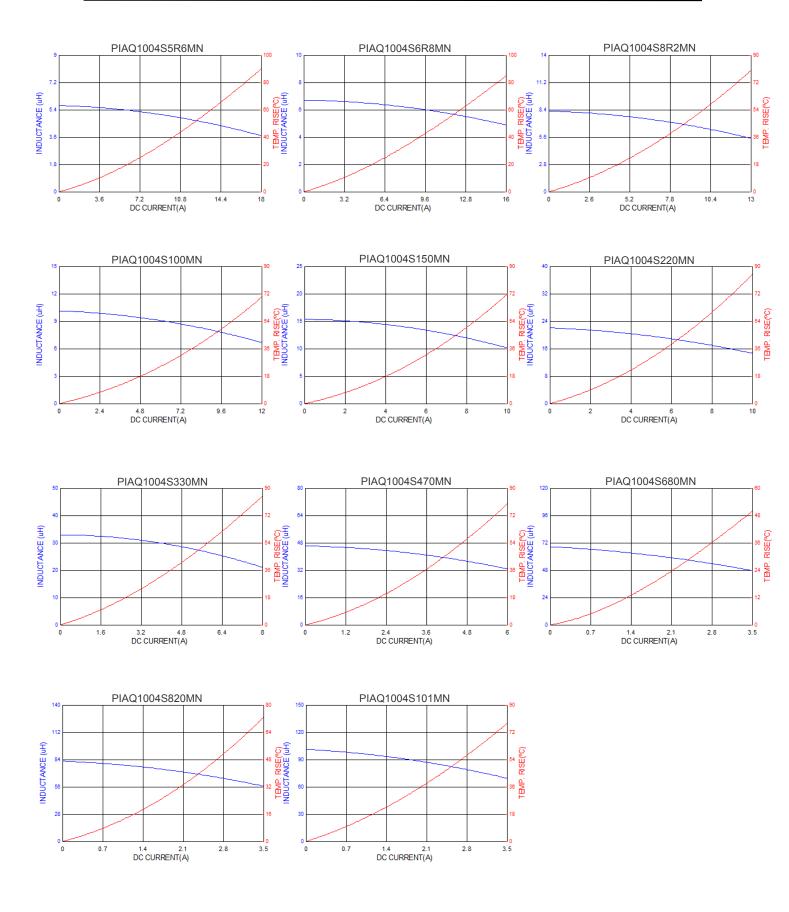
Notes:

1) At all times, the current supplied to the product should not exceed Isat Max. value.

# 7. Characteristics Curves:







## 8. Soldering:

Mildly activated rosin fluxes are preferred. The minimum amount of solder can lead to damage from the stresses caused by the difference in coefficients of expansion between solder, chip and substrate. Our terminations are suitable for all re-flow soldering systems. If hand soldering cannot be avoided, the preferred technique is the utilization of hot air.

#### 8-1 Solder Re-flow:

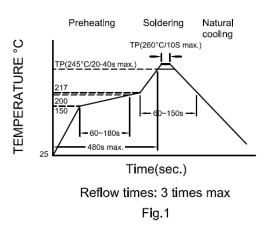
Recommended temperature profiles for re-flow soldering in Figure 1.

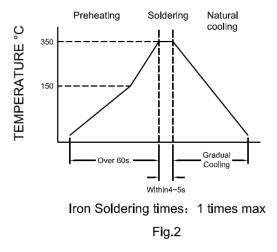
#### 8-2 Soldering Iron (Figure 2):

Products attachment with soldering iron is discouraged due to the inherent process control limitations. In the event that a soldering iron must be employed the following precautions are recommended.

Note :

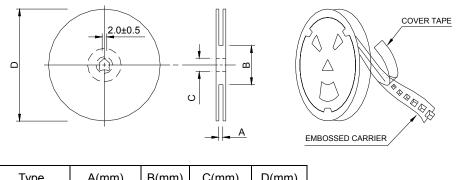
- a) Preheat circuit and products to 150°C.
- b) 355°C tip temperature (Max.)
- c) Never contact the ceramic with the iron tip
- d) 1.0mm tip diameter (Max.)
- e) Use a 20 watt soldering iron with tip diameter of 1.0mm
- f) Limit soldering time to 4~5 secs.





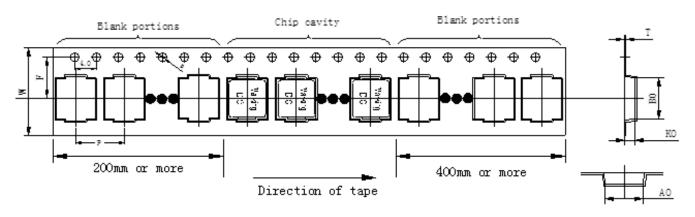
# 9. Packaging Information:

### 9-1 Reel Dimension:



Туре	A(mm)	B(mm)	C(mm)	D(mm)
13"x24mm	24.4+2/-0	100±2	13.5±0.5	330

#### 9-2 Tape Dimension:

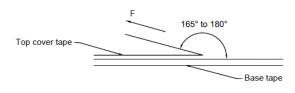


Series	Size	Bo(mm)	Ao(mm)	Ko(mm)	P(mm)	W(mm)	F(mm)	T(mm)	D(mm)
PIAQ	1004	11.6±0.1	10.4±0.1	4.5±0.1	16.0±0.1	24.0±0.3	11.5±0.1	0.35±0.05	1.5±0.1

### 9-3 Packaging Quantity:

PIAQ	1004
Chip / Reel	500
Inner box	1000
Carton	4000

### 9-4 Tearing Off Force:



The force for tearing off cover tape is 10 to 130 grams in the arrow direction under the following conditions (referenced ANSI/EIA-481-C-2003 of 4.11 standard).

Room Temp. (℃)	Room Humidity (%)	Room atm (hPa)	Tearing Speed mm/min
5~35	45~85	860~1060	300

## **Application Notice:**

1. Storage Conditions:

To maintain the solderabililty of terminal electrodes:

- a) Recommended products should be used within 12 months from the time of delivery.
- b) The packaging material should be kept where no chlorine or sulfur exists in the air.

#### 2. Transportation:

- a) Products should be handled with care to avoid damage or contamination from perspiration and skin oils.
- b) Vacuum pick up is strongly recommended for individual components.
- c) Bulk handling should ensure that abrasion and mechanical shock are minimized.